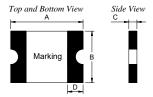
## 1, Physical Dimensions(size of 0805)

Unit: mm

Part Number	1	A	В		С		D	Marking	
Part Number	Min	Max	Min	Max	Min	Max	Min	Marking	
K0805L100/16AR	2.0	2.3	1.2	1.5	0.75	1.20	0.20	6	



#### 2. Electrical Characteristics

Part Number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	Ttrip (Max time to trip)  Current(A) Time(S)		Pd <sub>typ</sub> (W)	$R_{min} (\Omega)$	$R1_{max}$ $(\Omega)$
K0805L100/16AR	1.00	1.95	16.0	100	8.0	0.30	0.60	0.040	0.230

I<sub>H</sub>: Holding Current: maximum current at which the device will not trip in 25°C still air.

I<sub>T</sub>: Tripping Current minimum current at which the device will trip in 25°C still air.

V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

I max: Maximum fault current device can withstand without damage at rated voltage.

T trip: Maximum time to trip(s) at assigned current.

Pd<sub>typ</sub>: Rated working power.

R min: Minimum resistance of device prior to trip at 25°C.

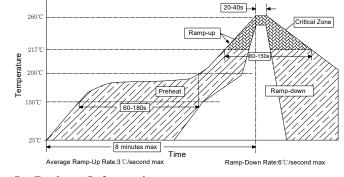
R1 max: Maximum resistance of device is measured one hours post reflow at 25°C.

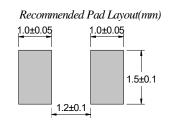
Noted: All electrical function test is conducted after PCB mounted.

## 3. Thermal Derating

K0805L100/16AR	Maximum ambient operating temperature									
	-40°C	-20°C	0℃	25℃	40℃	50℃	60℃	70°C	85℃	
Hold Current(A)	1.26	1.18	1.09	1.00	0.90	0.81	0.74	0.62	0.50	
Trip Current(A)	2.46	2.30	2.13	1.95	1.76	1.58	1.44	1.21	0.98	

## 4. Solder Reflow Recommendations





Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

# 5. Package Information

Packing quantity:3500PCS/Reel

Note: Reel packaging per EIA-481-1 standard